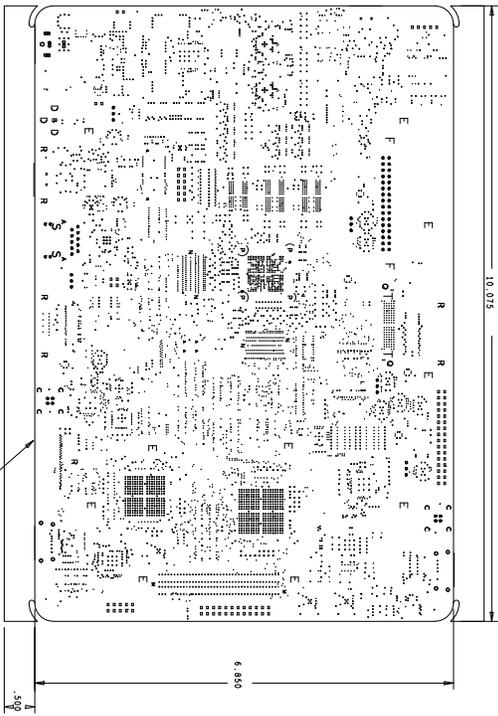
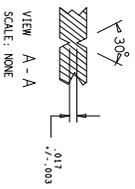


- TSLK
- SMC
- LAYER 1
- LAYER 2
- LAYER 3
- LAYER 4
- LAYER 5
- LAYER 6
- LAYER 7
- LAYER 8
- LAYER 9
- LAYER 10
- LAYER 11
- LAYER 12
- LAYER 13
- LAYER 14
- LAYER 15
- LAYER 16
- SMS
- BSLK

LAYER SCHEDULE
SCALE: NONE



SCORE LINE: 2 PLCS.



- NOTES: UNLESS OTHERWISE SPECIFIED
1. TOTAL BOARD THICKNESS SHALL BE .080 +/- .10% INCHES.
 2. ALL MATERIAL SHALL BE NEMA GRADE FR-4 OR EQUIVALENT. (19+170 DEG. C)
 3. REFER TO STACKUP DRAWING FOR COPPER WEIGHT.
 4. AVERAGE COPPER ON THE WALL OF THE PLATED HOLE SHALL BE PER IPC CLASS 2.
 5. MINIMUM CLEARANCE ON THE BOARD SHALL BE 3.0 MILS.
 6. MINIMUM TRACE WIDTH ON THE BOARD SHALL BE 3.0 MILS.
 7. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE S.M.O.B.C., LPT1, COLOR GREEN.
 8. PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH.
 9. UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
 10. DRC'S MUST BE RUN ON THE GERBERS BEFORE BUILDING BOARDS UNLESS PRIOR APPROVAL IS GIVEN IN WRITING.
 11. FINISHED BOARD SHALL BE FREE OF BURNS ON EDGES.
 12. SURFACE FINISH SHALL BE IMMERSION GOLD.
 13. IMPEDANCE CONTROL: REFER TO STACKUP DRAWING FOR IMPEDANCE CONTROL.

DRILL CHART
ALL UNITS ARE IN MILS.

FIGURE	SIZE	PLATED	QTY	TOL	NOTE
A	8.0	PLATED	3039		
B	10.0	PLATED	2738		
C	12.0	PLATED	334		
D	13.0	PLATED	141		
E	18.0	PLATED	9		
F	38.0	PLATED	61		
G	39.0	PLATED	8		
H	40.0	PLATED	91		
I	51.0	PLATED	8		
J	62.0	PLATED	2		
K	67.0	PLATED	8		
L	102.0	PLATED	3		
M	125.0	PLATED	10		
N	138.0	PLATED	2		
O	34.0	NON-PLATED	2		
P	35.0	NON-PLATED	2		
Q	35.43	NON-PLATED	2		
R	40.0	NON-PLATED	2		
S	41.0	NON-PLATED	2		
T	50.0	NON-PLATED	2		
U	57.09	NON-PLATED	4		
V	63.0	NON-PLATED	1		
W	70.0	NON-PLATED	4		
X	82.68	NON-PLATED	2		
Y	93.0	NON-PLATED	7		
Z	126.0	NON-PLATED	2		
AA	137.8	NON-PLATED	2		
AB	148.0	PLATED	2		
AC	158.0	PLATED	1		

9-19-16

TECHNICAL CENTER
INDUSTRY PARTS
KICK & BISS
RUEBENS 1727

DO NOT SCALE DRAWING

SPECTRUM DIGITAL

FABRICATION DRAWING,
TDA3x/DRA78x/DM50x-15X15 EVM

SCALE

SHEET

517541 REV E

1 2 3 4 5 6 7 8 9 10 11

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